



## Material Content Data Sheet



<b>Sales Product Name</b>		BSP772T		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA001070980						
<b>Package</b>		PG-DSO-8-24		<b>Weight*</b>		83.54 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.222	3.86	3.86	38569	38569
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		107	
	non noble metal	zinc	7440-66-6	0.036	0.04		429	
	non noble metal	iron	7439-89-6	0.717	0.86		8585	
wire	non noble metal	copper	7440-50-8	29.121	34.86	35.77	348596	357717
	noble metal	gold	7440-57-5	0.410	0.49	0.49	4904	4904
	encapsulation	organic material	carbon black	1333-86-4	0.095	0.11		1139
plastics	plastics	epoxy resin	-	4.378	5.24		52409	
		silicondioxide	60676-86-0	43.115	51.62	56.97	516115	569663
leadfinish	non noble metal	tin	7440-31-5	0.814	0.97	0.97	9742	9742
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7784	7784
glue	plastics	epoxy resin	-	0.170	0.20		2034	
		noble metal	silver	7440-22-4	0.801	0.96	1.16	9587
*deviation	< 10%					Sum in total:	100,00	1000000

### Important Remarks:

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